



Material Content Data Sheet



Sales Product Name		IPG20N06S4L-26		Issued		22. January 2018		
MA#		MA001663544						
Package		PG-TDSON-8-4		Weight*		96.37 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.567	1.63	1.63	16257	16257
leadframe	non noble metal	iron	7439-89-6	0.045	0.05		464	
	inorganic material	phosphorus	7723-14-0	0.013	0.01		139	
	non noble metal	copper	7440-50-8	44.654	46.34	46.40	463365	463971
wire	non noble metal	aluminium	7429-90-5	0.724	0.75	0.75	7510	7510
encapsulation	organic material	carbon black	1333-86-4	0.091	0.09		947	
	plastics	epoxy resin	-	6.479	6.72		67228	
	inorganic material	silicondioxide	60676-86-0	39.055	40.53	47.34	405264	473439
leadfinish	non noble metal	tin	7440-31-5	1.308	1.36	1.36	13569	13569
plating	non noble metal	nickel	7440-02-0	0.048	0.05		498	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.05	1	499
solder	noble metal	silver	7440-22-4	0.060	0.06		619	
	non noble metal	tin	7440-31-5	0.048	0.05		495	
	non noble metal	lead	7439-92-1	2.278	2.36	2.47	23641	24755
heatspreader	non noble metal	copper	7440-50-8	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		1	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.00	1	0
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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